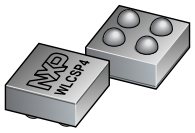


SOT1375-6

WLCSP4, wafer level chip-scale package, 4 terminals, 0.4 mm pitch, 0.91 mm x 0.855 mm x 0.455 mm body (backside coating included)

5 August 2022 **Package information**

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP4
Package style descriptive code	WLCSP (wafer level chip-size package)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	15-07-2022
Manufacturer package code	98ASA01775D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	0.91	-	mm
package width	-	0.855	-	mm
seated height	-	0.455	0.485	mm
nominal pitch	-	0.4	-	mm

WLCSP4, wafer level chip-scale package, 4 terminals, 0.4 mm pitch, 0.91 mm x 0.855 mm x 0.455 mm body (backside coating included)

2 Package outline

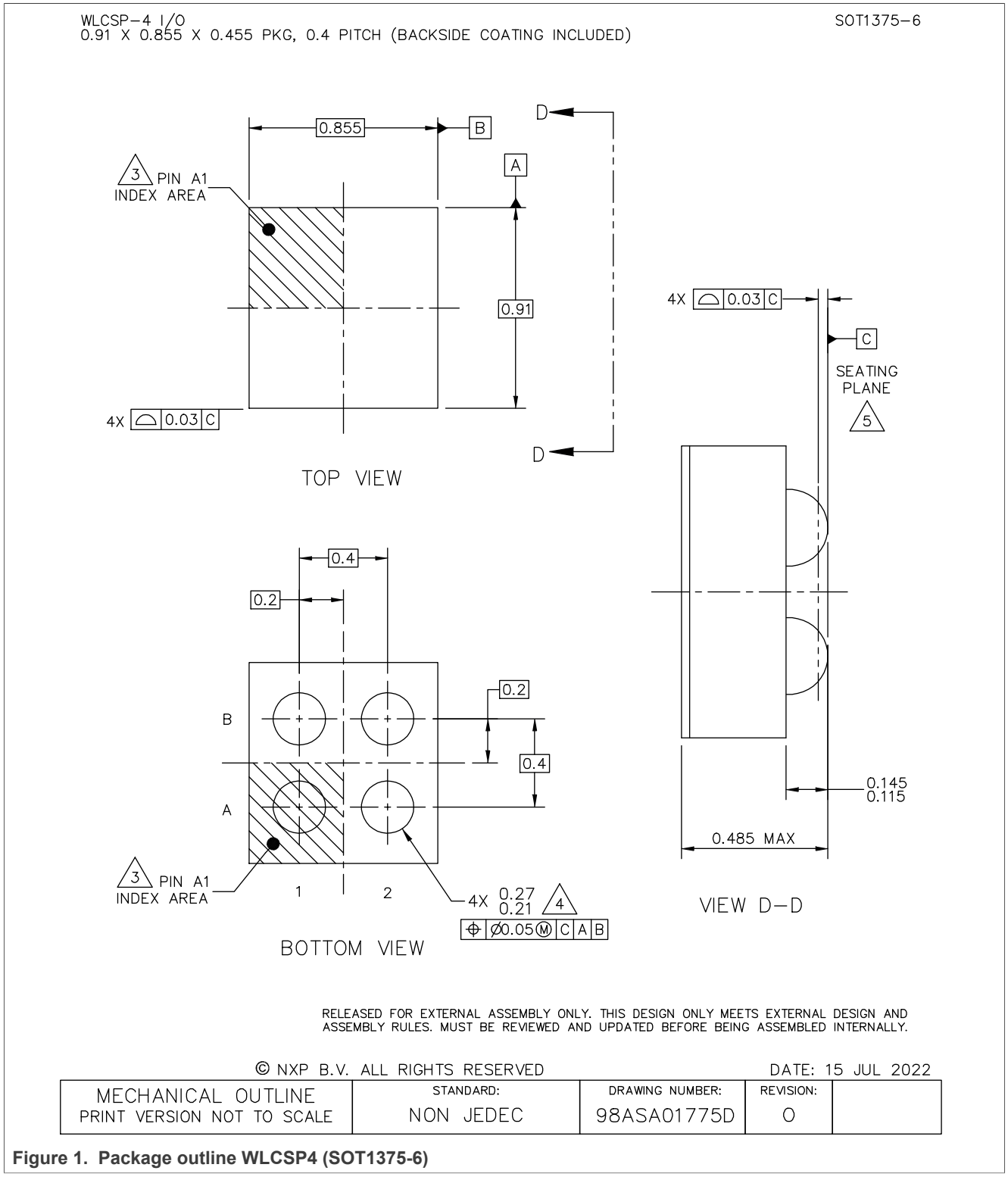


Figure 1. Package outline WLCSP4 (SOT1375-6)

3 Soldering

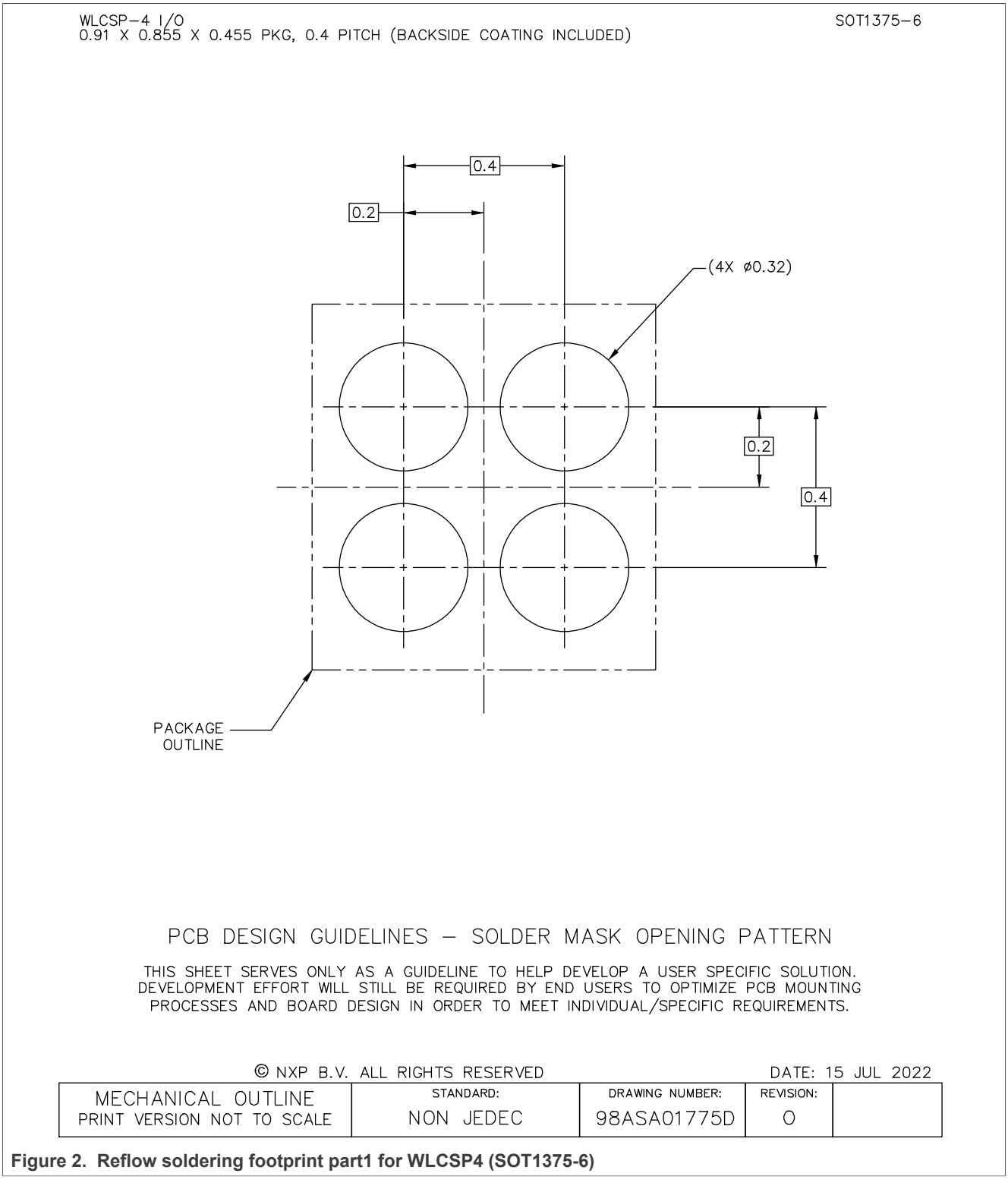
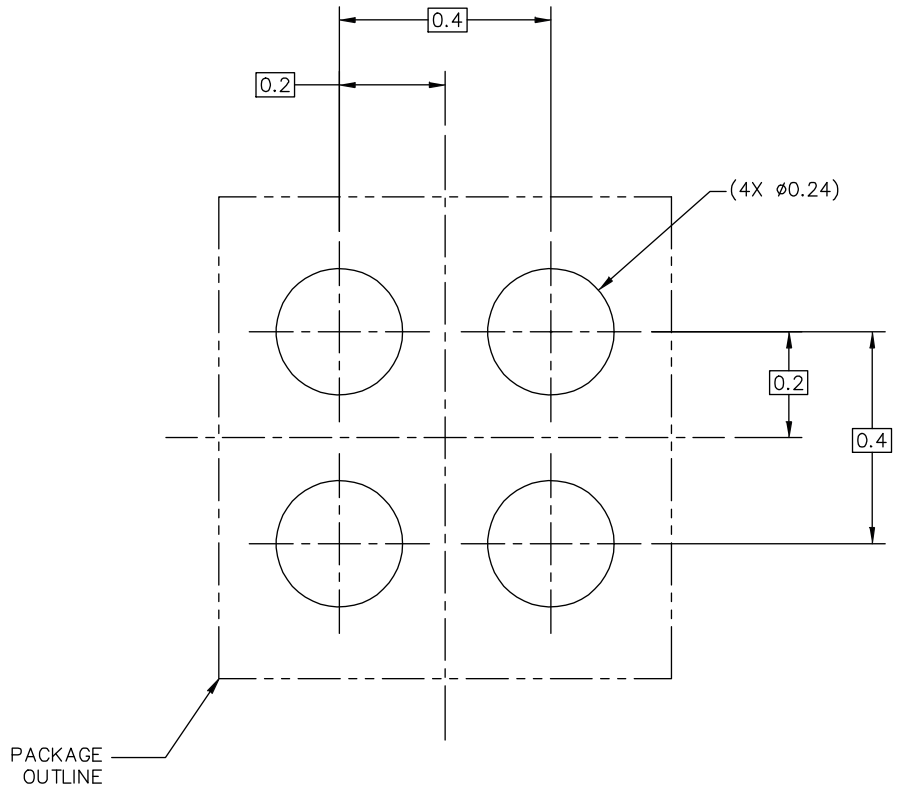


Figure 2. Reflow soldering footprint part1 for WLCSP4 (SOT1375-6)

WLCSP4, wafer level chip-scale package, 4 terminals, 0.4 mm pitch, 0.91 mm x 0.855 mm x 0.455 mm body (backside coating included)

WLCSP−4 I/O
0.91 X 0.855 X 0.455 PKG, 0.4 PITCH (BACKSIDE COATING INCLUDED)

SOT1375−6



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DATE: 15 JUL 2022

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01775D	REVISION: O	

Figure 3. Reflow soldering footprint part2 for WLCSP4 (SOT1375-6)

WLCSP4, wafer level chip-scale package, 4 terminals, 0.4 mm pitch, 0.91 mm x 0.855 mm x 0.455 mm body (backside coating included)

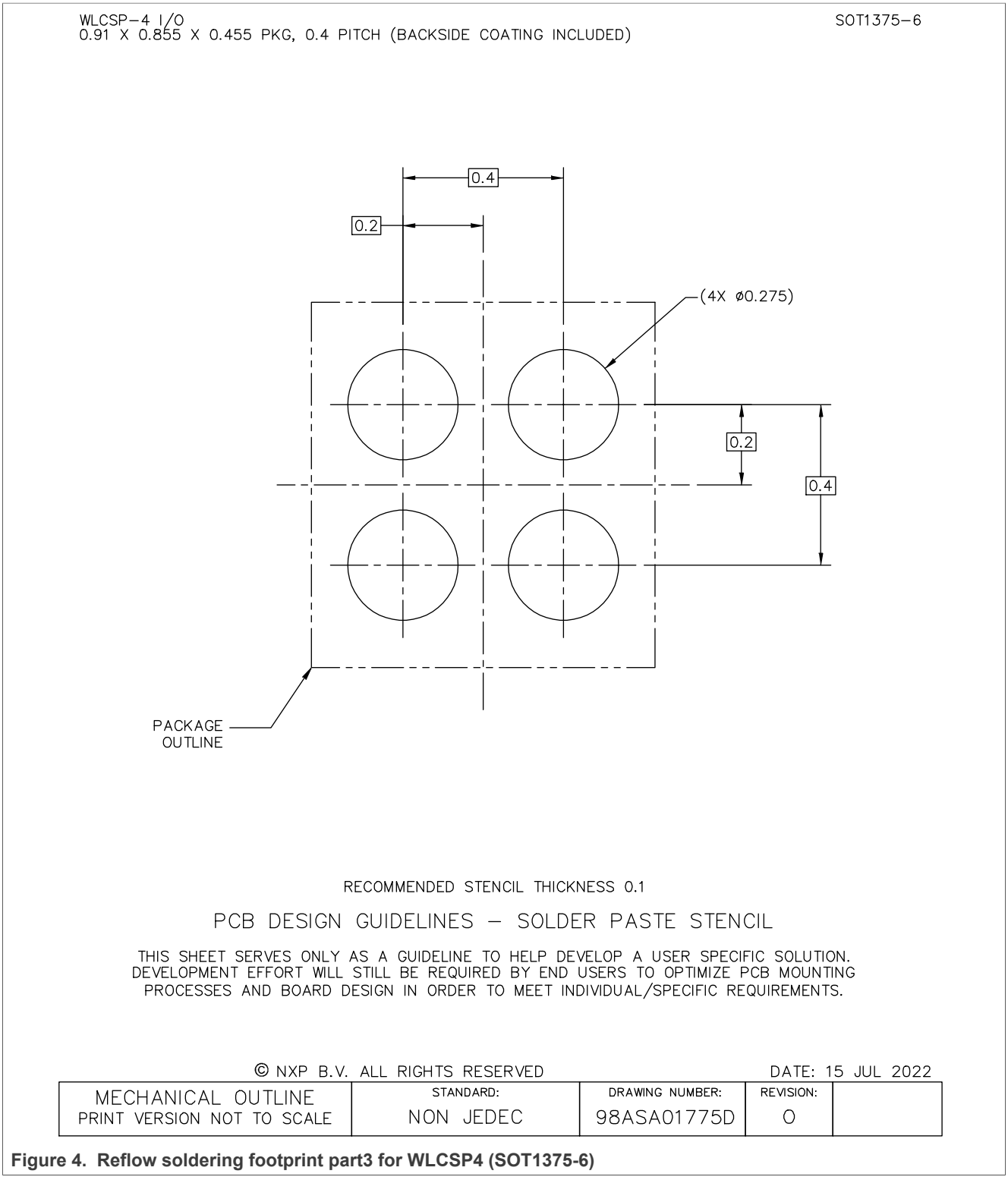

Figure 4. Reflow soldering footprint part3 for WLCSP4 (SOT1375-6)

WLCSP4, wafer level chip-scale package, 4 terminals, 0.4 mm pitch, 0.91 mm x 0.855 mm x 0.455 mm body (backside coating included)

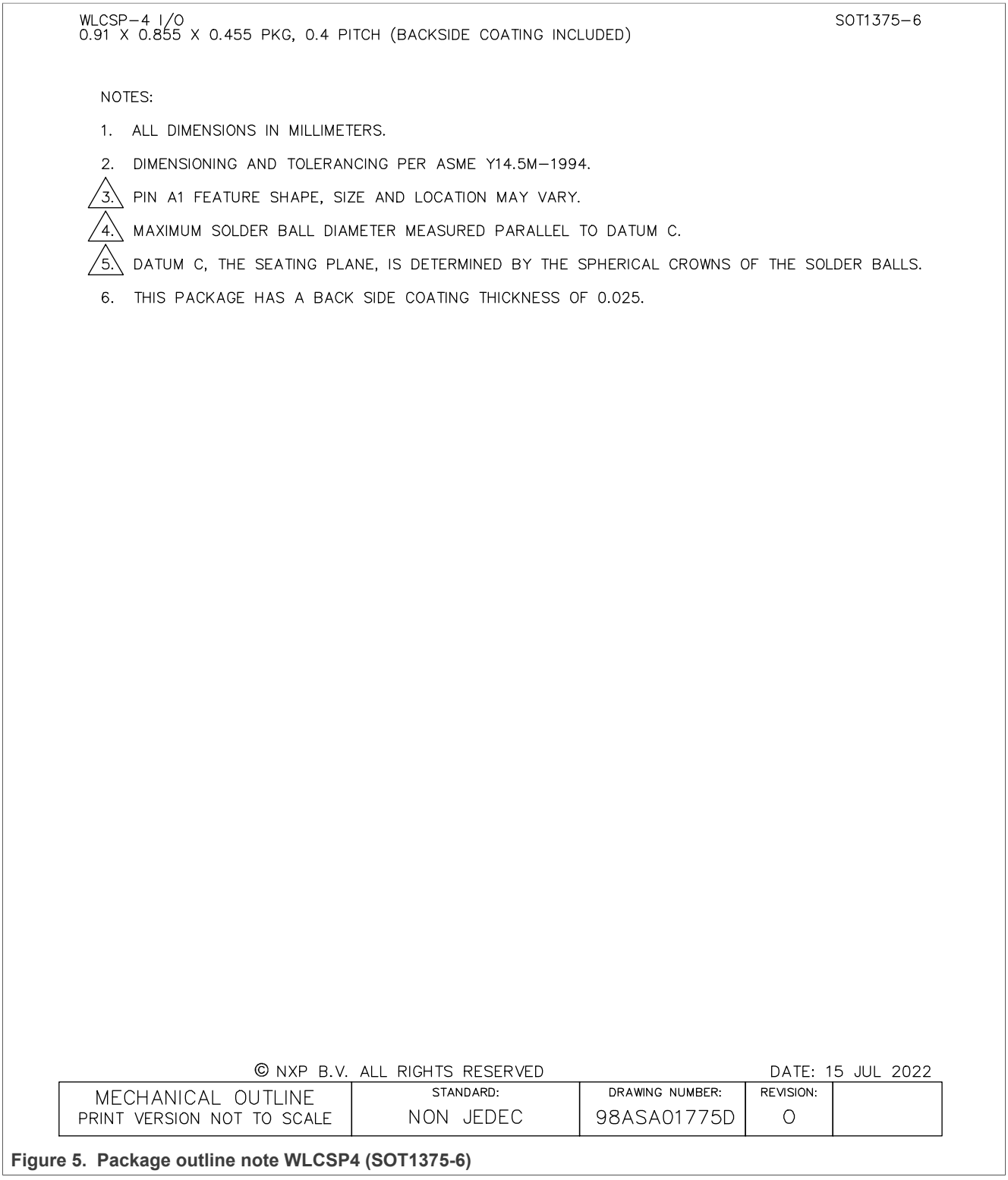

Figure 5. Package outline note WLCSP4 (SOT1375-6)

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SOT1375-6

WLCSP4, wafer level chip-scale package, 4 terminals, 0.4 mm pitch, 0.91 mm x 0.855 mm x 0.455 mm body (backside coating included)

Contents

For more information, please visit: http://www.nxp.com
For sales office addresses, please send an email to: salesaddresses@nxp.com

Date of release: 5 August 2022